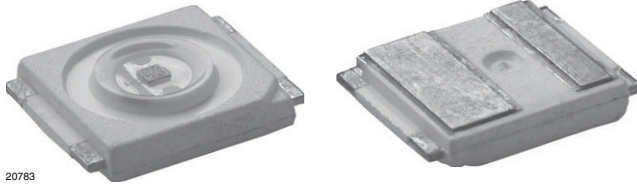




# High Power Infrared Emitting Diode, 850 nm, Surface Emitter Technology



20783

## DESCRIPTION

As part of the [SurfLight™](#) portfolio, the VSMY7852X01 is an infrared, 850 nm emitting diode based on surface emitter technology with high radiant power and high speed, molded in low thermal resistance Little Star package. A 20 mil chip provides outstanding low forward voltage and allows DC operation of the device up to 250 mA.

## APPLICATIONS

- Infrared illumination for CMOS cameras (CCTV)
- Machine vision IR data transmission

## FEATURES

- Package type: surface-mount
- Package form: Little Star®
- Dimensions (L x W x H in mm): 6.0 x 7.0 x 1.5
- Peak wavelength:  $\lambda_p = 850$  nm
- High reliability
- High radiant power
- High radiant intensity
- Angle of half intensity:  $\phi = \pm 60^\circ$
- Low forward voltage
- Designed for high drive currents: up to 250 mA DC and up to 1.5 A pulses
- Low thermal resistance:  $R_{thJP} = 15$  K/W
- Floor life: 1 year, MSL 2, according to J-STD-020
- Lead (Pb)-free reflow soldering
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



RoHS COMPLIANT

PRODUCT SUMMARY				
COMPONENT	$I_e$ (mW/sr)	$\phi$ (deg)	$\lambda_p$ (nm)	$t_r$ (ns)
VSMY7852X01	55	$\pm 60$	850	8

### Note

- Test conditions see table "Basic Characteristics"

ORDERING INFORMATION			
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
VSMY7852X01-GS08	Tape and reel	MOQ: 2000 pcs, 2000 pcs/reel	Little Star

### Note

- MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS ( $T_{amb} = 25$ °C, unless otherwise specified)				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		$V_R$	5	V
Forward current		$I_F$	250	mA
Peak forward current	$t_p/T = 0.5, t_p = 100$ $\mu$ s	$I_{FM}$	500	mA
Surge forward current	$t_p = 100$ $\mu$ s	$I_{FSM}$	1.5	A
Power dissipation		$P_V$	500	mW
Junction temperature		$T_j$	125	°C
Operating temperature range		$T_{amb}$	-40 to +100	°C
Storage temperature range		$T_{stg}$	-40 to +100	°C
Soldering temperature	According to Fig. 7, J-STD-20	$T_{sd}$	260	°C
Thermal resistance junction-to-pin	According to J-STD-051, soldered on PCB	$R_{thJP}$	15	K/W

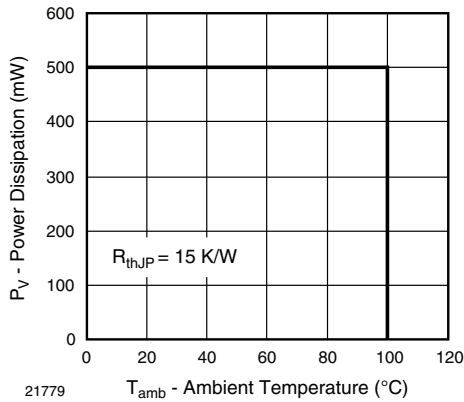


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

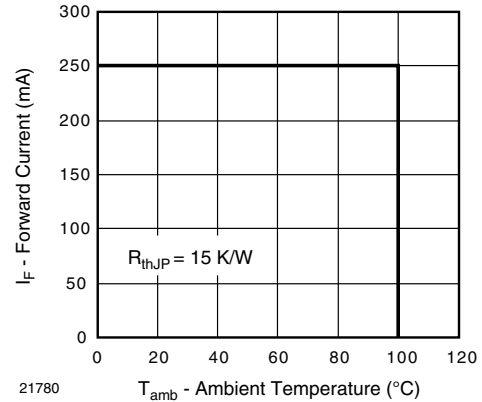


Fig. 2 - Forward Current Limit vs. Ambient Temperature

BASIC CHARACTERISTICS ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	$I_F = 250\text{ mA}$ , $t_p = 10\text{ ms}$	$V_F$	-	1.7	2.0	V
Temperature coefficient of $V_F$	$I_F = 1\text{ mA}$	$TK_{V_F}$	-	-1.5	-	mV/K
Reverse current	$V_R = 5\text{ V}$	$I_R$	Not designed for reverse operation			$\mu\text{A}$
Radiant intensity	$I_F = 250\text{ mA}$ , $t_p = 10\text{ ms}$	$I_e$	30	55	90	mW/sr
Radiant power	$I_F = 250\text{ mA}$ , $t_p = 20\text{ ms}$	$\phi_e$	-	130	-	mW
Temperature coefficient of $\phi_e$	$I_F = 1\text{ A}$	$TK_{\phi_e}$	-	-0.5	-	%/K
Angle of half intensity		$\phi$	-	$\pm 60$	-	deg
Peak wavelength	$I_F = 250\text{ mA}$	$\lambda_p$	-	850	-	nm
Spectral bandwidth	$I_F = 250\text{ mA}$	$\Delta\lambda$	-	30	-	nm
Temperature coefficient of $\lambda_p$	$I_F = 250\text{ mA}$	$TK_{\lambda_p}$	-	0.2	-	nm/K
Rise time	$I_F = 250\text{ mA}$	$t_r$	-	8	-	ns
Fall time	$I_F = 250\text{ mA}$	$t_f$	-	10	-	ns

**BASIC CHARACTERISTICS** ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified)

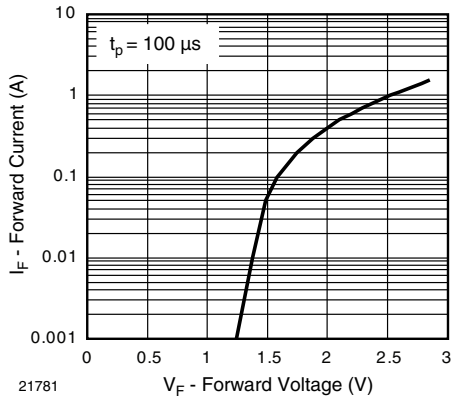


Fig. 3 - Forward Current vs. Forward Voltage

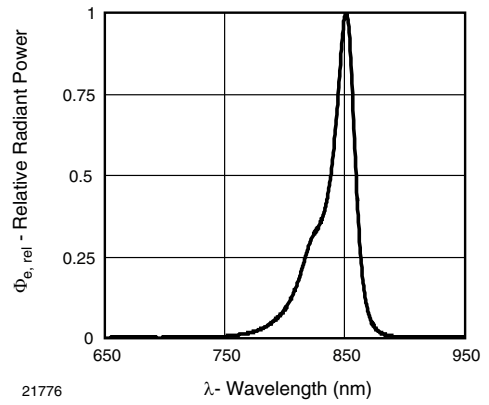


Fig. 5 - Relative Radiant Power vs. Wavelength

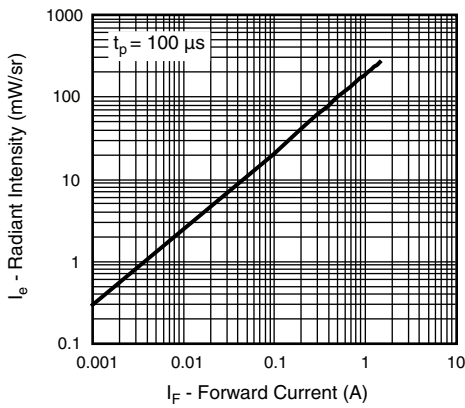


Fig. 4 - Radiant Intensity vs. Forward Current

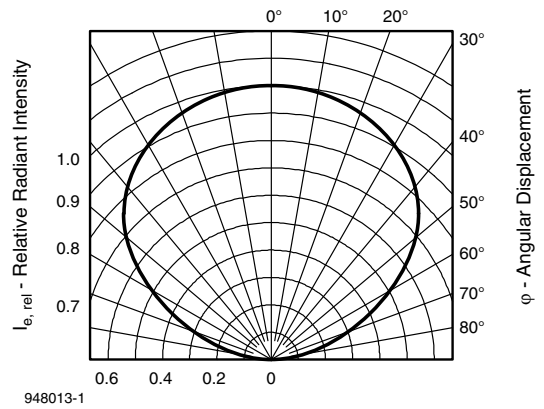
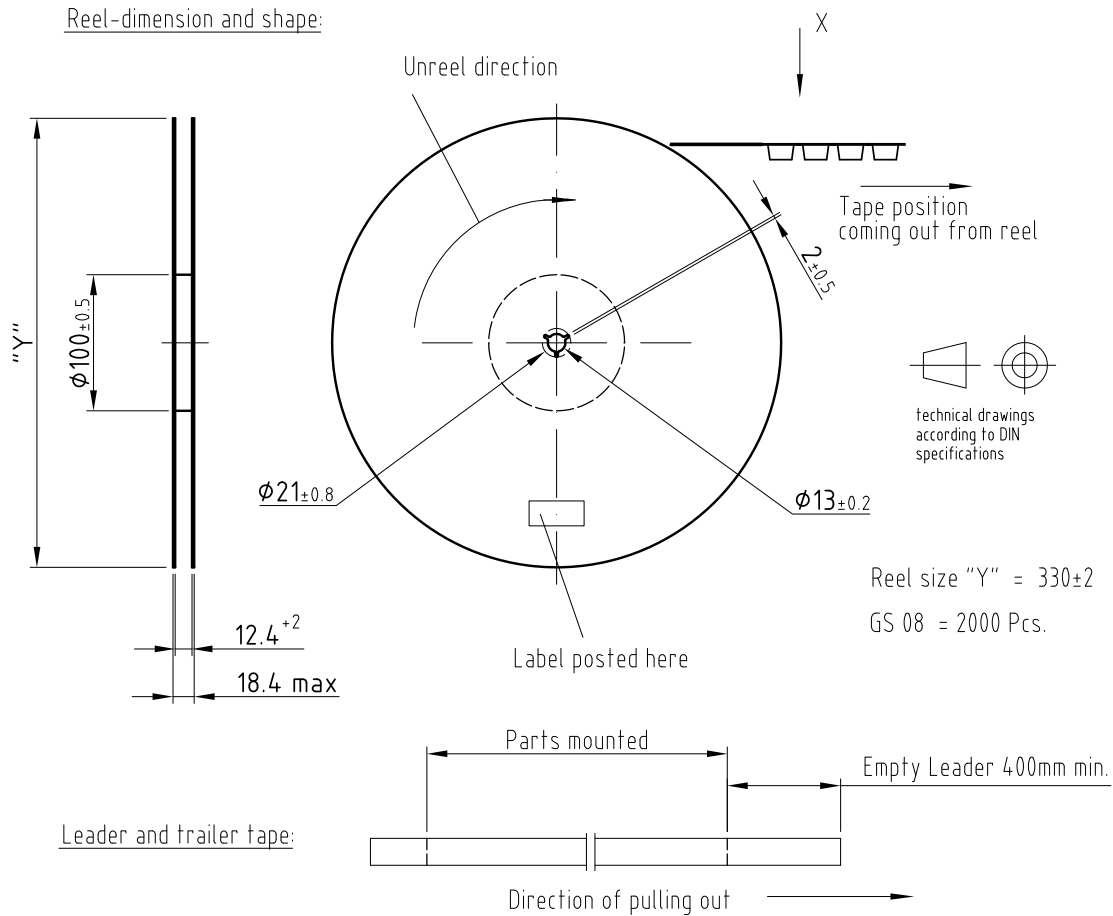
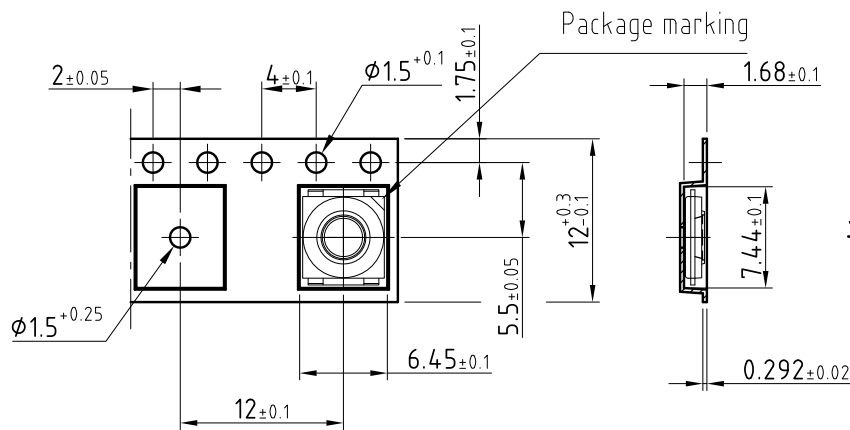


Fig. 6 - Relative Radiant Intensity vs. Angular Displacement

**TAPING DIMENSIONS** in millimeters



Leader and trailer tape:



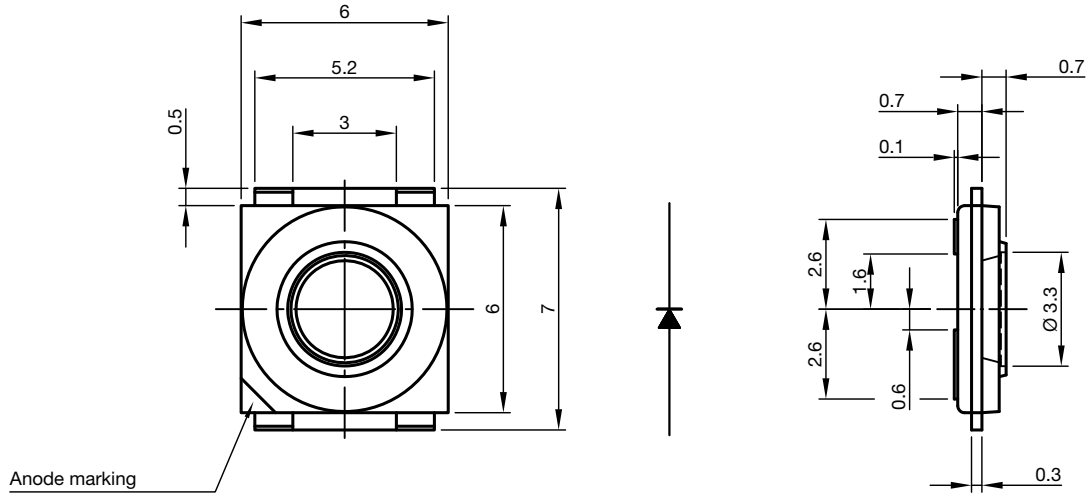
Drawing-No: 9.800-5094.01-4

Issue: 3; 22.01.08

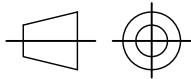
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PACKAGE DIMENSIONS in millimeters



Anode marking



technical drawings according to DIN specifications

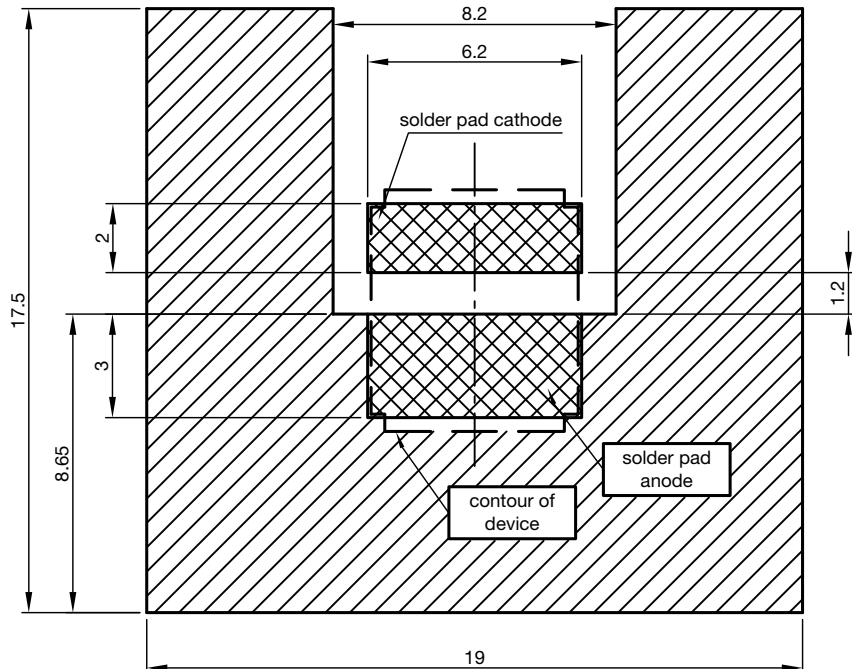
Recommended solder pad



Recommended area for heat sink connected with anode pad



Not indicated tolerances  $\pm 0.1$



Drawing-No.: 6.541-5076.01-4  
Issue: 3; 22.10.14

**SOLDER PROFILE**

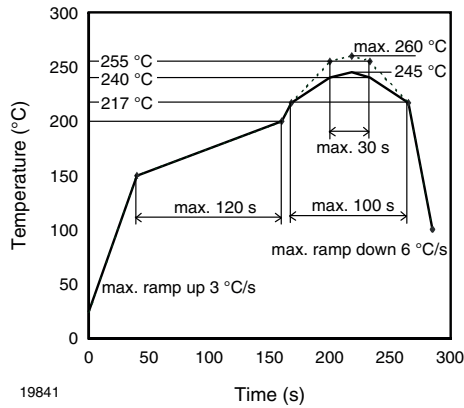


Fig. 7 - Lead (Pb)-free Reflow Solder Profile According to J-STD-020 for Preconditioning According to JEDEC®, Level 2

**DRYPACK**

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

**FLOOR LIFE**

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 1 year

Conditions:  $T_{amb} < 30\text{ °C}$ ,  $RH < 60\%$

Moisture sensitivity level 2, according to J-STD-020B

**DRYING**

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 °C (+ 5 °C),  $RH < 5\%$ .



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